

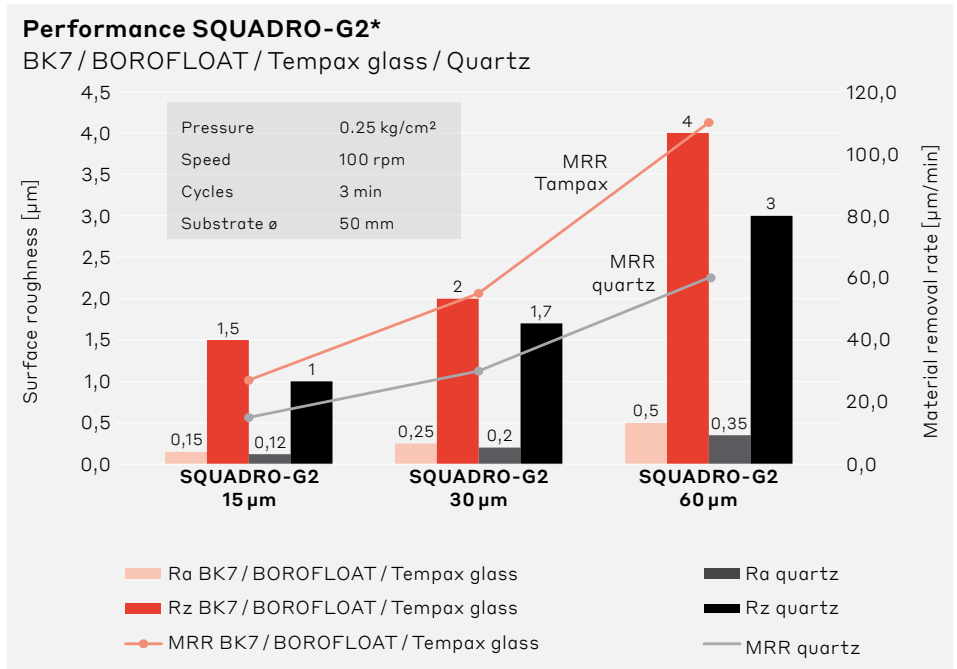
Highlights

- Suited for all common glass materials
- All outer diameters possible
- Outstanding lifetime and economic efficiency compared to the competition
- New generation with 50 % more grinding layer
- Cleaner than lapping with grinding suspensions
- High planarity, surface quality and precise edges

Diamond grinding pad

SQUADRO-G2

SQUADRO-G2 is the second generation of the innovative and highly efficient SQUADRO-G diamond grinding pad. Its new manufacturing process allows greater flexibility in the production of different diameters. It has 50 % more grinding thickness, which significantly increases the lifetime. In terms of application, SQUADRO-G2 offers high and uniform stock removal throughout its lifetime, as well as impressive surface qualities and edge sharpening. Thanks to its long lifetime and easy handling, SQUADRO-G2 is an economical and efficient alternative to other grinding pads or conventional lapping methods.



*Double sided lapping on Peter Wolters AC-400 machine in Pureon's Surface Lab



SQUADRO-G2 grinding pad



Glass wafer, type BK7



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Product specifications

Abrasive layer thickness 0,6 mm
 Bond type Resin
 Carrier material Polycarbonate
 Typical application Optical glass, BK7, quartz glass, glass ceramics, crystalline and brittle glassy materials

Order information

Order code SQUADRO-G2 15-OD475-ID200mm-PU1-PSA-D1
1 2 3 4 5 6

- 1 Diamond size 15 µm, 30 µm, 45 µm, 60 µm
- 2 Outer diameter 200 – 1'200 mm one-piece
 For bigger diameters multi-piece
 Custom sizes are available upon request
- 3 Inner diameter Optional (freely selectable)
- 4 Packing unit 1 piece / box
- 5 Backing / mounting PSA (self-adhesive)
 SGM (metal plate)
 MAG (magnetic foil)
- 6 Drawing index Optional

Application recommendations

Dressing Prior to the first use, the SQUADRO-G2 pad has to be dressed and planarized with a dressing tool (e.g. Al₂O₃ with grit 280 mesh (grit size 45 µm, 60 µm) or 400 mesh (grit size 15 µm, 30 µm)).

Cleaning To ensure cutting efficiency of the bonding, the grinding pad has to be cleaned from abrasive debris regularly. Best suited for this are brass brushes for manual or machine use. Machine brushes can be ordered from Pureon as accessories.

Coolant SQUADRO-LUB+ is recommended and a water-soluble cooling and lubricating fluid that ensures high and consistent material removal. DI-water is only partly suited. No dry running. Organic solvent and oil based lubricants may harm the pad and are therefore not recommended.

Grinding parameters

Grinding pressure Recommended: 0.2 – 1 kg/cm², max. 1.5 kg/cm²
 Circumferential speed Recommended: 5 m/s, max. 10 m/s

Contact

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